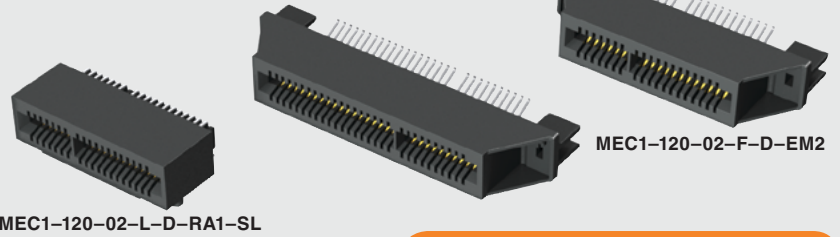


MEC1-130-02-L-D-EM2



MEC1-120-02-F-D-EM2

MEC1-120-02-L-D-RA1-SL

MEC1-RA, MEC1-EM SERIES

(1.00 mm) .0394"

RIGHT-ANGLE/EDGE MOUNT SOCKETS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC1-RA

Insulator Material: Black LCP
Contact Material: Phosphor Bronze
Plating: Au or Sn over 50 μ" (1.27 μm) Ni
Current Rating: 1.6 A per pin (2 adjacent pins powered)
Operating Temp Range: -55 °C to +125 °C
Insertion Depth: (5.84 mm) .230" to (8.13 mm) .320"
RoHS Compliant: Yes

PROCESSING

Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0.10 mm) .004" max (05-40) (0.15 mm) .006" max (50-70)*
 *(.004" stencil solution may be available; contact IPG@samtec.com)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



MEC1 - **1** POSITIONS PER ROW - **CARD SLOT** - **PLATING OPTION** - **D** - **RA1** - **NP** - **SL**

Mates with:
 (1.60 mm)
 .062" card

05, 08, 20, 30,
 40, 50, 60, 70

-02
 = (1.60 mm)
 .062" thick card

-F
 = Gold flash on contact,
 Matte Tin on tail

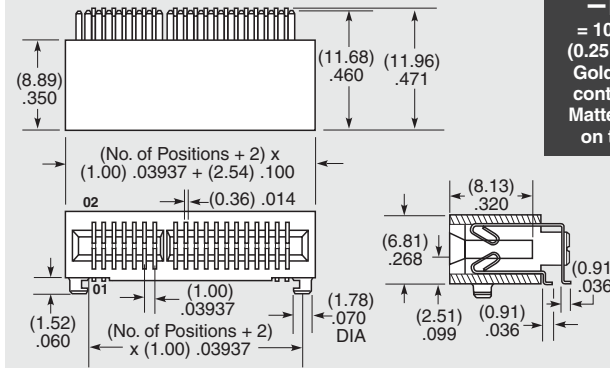
-L
 = 10 μ" (0.25 μm)
 Gold on contact,
 Matte Tin on tail

POSITIONS PER ROW	POLARIZED POSITIONS
05	3, 4
08	5, 6
20	15, 16
30	21, 22
40	31, 32
50	41, 42
60	31, 32, 63 & 64
70	53, 54, 115 & 116

-NP
 = No Polarization
 (8 positions only)
 Leave Blank for polarization

ALSO AVAILABLE (MOQ Required)

- Elevated body height
- Other platings



Note: Some sizes, styles and options are non-standard, non-returnable.

Note: While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications.

HIGH-SPEED CHANNEL PERFORMANCE

MEC1-RA

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

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 G b p s

APPLICATION

Samtec recommends that pads on the mating board be Gold plated.

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC1-EM

Insulator Material: Black LCP
Contact Material: Phosphor Bronze
Plating: Au or Sn over 50 μ" (1.27 μm) Ni
Current Rating: 1.8 A per pin (2 adjacent pins powered)
Operating Temp Range: -55 °C to +125 °C
Insertion Depth: (5.84 mm) .230" to (8.13 mm) .320"
RoHS Compliant: Yes

Lead-Free Solderable: Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



MEC1 - **1** POSITIONS PER ROW - **02** - **PLATING OPTION** - **D** - **EM2** - **NP**

Mates with:
 (1.60 mm)
 .062" card

05, 08, 20, 30,
 40, 50, 60, 70

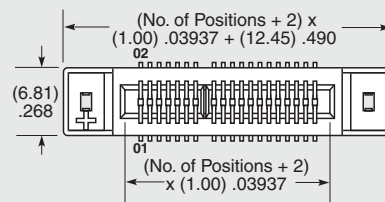
-F
 = Gold flash on contact,
 Matte Tin on tail

-L
 = 10 μ" (0.25 μm) Gold on contact,
 Matte Tin on tail

-NP
 = No Polarization
 (8 positions only)
 Leave Blank for polarization

ALSO AVAILABLE (MOQ Required)

- Edge mount leads for (0.80 mm) .031" thick board
- Other platings



Note: Some sizes, styles and options are non-standard, non-returnable.

Note: While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications.

POSITIONS PER ROW	POLARIZED POSITIONS
05	3, 4
08	5, 6
20	15, 16
30	21, 22
40	31, 32
50	41, 42
60	31, 32, 63 & 64
70	53, 54, 115 & 116

Due to technical progress, all designs, specifications and components are subject to change without notice.